

# Principal / Senior Engineer, New Product Introduction - Wafer Technology, Technical Operations Management

## Responsabilități

The Principal / Senior Engineer for New Product Introduction - Wafer Technology is responsible for overseeing semiconductor technology development and implementation. This role demands exceptional technical expertise to ensure the successful transition of products from concept to mass production.

- Lead NPI process from Concept to Mass Production at Foundry (especially BCD, RF-CMOS), ensure collaboration between design, engineering, and manufacturing teams to maximize semiconductor technology optimization.
- Ensure compliance with design rules and specifications while planning and evaluating silicon characterization results.
- Develop and implement robust qualification processes, including the establishment of wafer acceptance criteria and comprehensive testing protocols.
- Lead yield improvement initiatives through in-depth analysis of test data and resolution of issues encountered during the NPI process.
- Produce comprehensive reports detailing project status, potential risks, and key milestones; execute thorough risk assessments for foundry excursions and return material authorizations.
- Implement and oversee sophisticated data exchange protocols between foundry, Outsourced Semiconductor Assembly and Test (OSAT) providers, and Continental to facilitate effective yield monitoring and quality control.
- Drive continuous improvement in wafer technology processes, identifying opportunities for enhanced efficiency, cost reduction, and quality improvement.
- Develop and maintain strong relationships with key suppliers and technology partners, staying abreast of industry trends and emerging technologies in semiconductor manufacturing.

# Cerințe

- Degree in Electronics/Electrical Engineering (or relevant) with minimum five years' working experience in semiconductor (e.g., process or product), or subcon management (e.g., Foundries or OSAT).
- Good knowledge in semiconductor manufacturing processes (e.g., wafer process technologies and package assembly), electronic testing (e.g., DFT, Test Hardware, Test Development) and automotive electronic qualification requirements (e.g., AEC-Q100/101).
- Preferable with strong technical proficiency in wafer manufacturing, process integration and/or device engineering.
- Good interpersonal and communication skills (e.g., Business English, Presentations) to interact with internal and external stakeholders.
- Strong problem-solving skills, results oriented and a quality-focused



Job ID REF84265C

ID poziție Inginerie

Domeniul de activitate **Singapore** 

Nivelul de Leadership **Leading Self** 

Flexibilitatea programului de lucru

Onsite Job

Persoană juridică Continental Automotive Singapore Pte. Ltd. mindset.

 Team player with proactive attitude, able to work independently and travel frequently.

#### Oferta noastră

Ready to drive with Continental? Take the first step and fill in the online application.

### Despre noi

Continental develops pioneering technologies and services for sustainable and connected mobility of people and their goods. Founded in 1871, the technology company offers safe, efficient, intelligent and affordable solutions for vehicles, machines, traffic and transportation. In 2024, Continental generated sales of €39.7 billion and currently employs around 190,000 people in 55 countries and markets.

The Automotive group sector comprises technologies for passive safety, brake, chassis, motion and motion control systems. Innovative solutions for assisted and automated driving, display and operating technologies, as well as audio and camera solutions for the vehicle interior, are also part of the portfolio, as is intelligent information and communication technology for the mobility services of fleet operators and commercial vehicle manufacturers. Comprehensive activities relating to connectivity technologies, vehicle electronics and high-performance computers round off the range of products and services.